X-1335 US PATENT

A PROGRAMMABLE MULTI-CHIP MODULE

ABSTRACT

A multi-chip module comprising: a first IC having a first column of tiles, where each tile includes programmable logic; a second IC having a second column of tiles, where the second column is aligned with the first column; and a carrier die having signal lines, where a tile in the first column is directly connected to a tile in the second column via one of the signal lines.